



SEMITRANS® 6

IGBT modules

SKM25GD125D

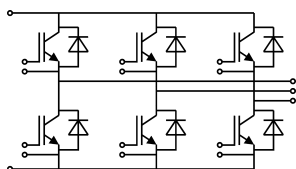
Target Data

Features

- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_{Cnom}$
- Fast & soft inverse CAL diodes
- Large clearance (10 mm) and creepage distances (20 mm)
- Isolated copper baseplate using DBC Technology (Direct Copper Bonding)
- UL recognized, file no. E63532

Typical Applications*

- Three phase inverters for AC motor speed control
- Pulse frequencies also above 15 kHz
- DC servo and robot drives



GD

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 150 °C	T _c = 25 °C	39	A
		T _c = 80 °C	27	A
I _{Cnom}			25	A
I _{CRM}	I _{CRM} = 2xI _{Cnom}		50	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 600 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 125 °C	10	μs
T _j			-55 ... 150	°C
Inverse diode				
I _F	T _j = 150 °C	T _c = 25 °C	47	A
		T _c = 80 °C	32	A
I _{Fnom}			40	A
I _{FRM}	I _{FRM} = 2xI _{Fnom}		80	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		410	A
T _j			-40 ... 150	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C		100	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50 Hz, t = 1 min		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 25 A	T _j = 25 °C		3.20	3.70	V
	V _{GE} = 15 V chiplevel	T _j = 125 °C		3.60	4.20	V
V _{CE0}	chiplevel	T _j = 25 °C		1.5	1.75	V
		T _j = 125 °C		1.7	1.95	V
r _{CE}	V _{GE} = 15 V chiplevel	T _j = 25 °C		68.00	78.00	mΩ
		T _j = 125 °C		76.00	90.00	mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 1 mA		4.5	5.5	6.5	V
I _{CES}	V _{GE} = 0 V	T _j = 25 °C		0.1	0.3	mA
	V _{CE} = 1200 V					mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		1.65		nF
C _{oes}		f = 1 MHz		0.25		nF
C _{res}		f = 1 MHz		0.11		nF
Q _G	V _{GE} = - 8 V...+ 20 V			221		nC
R _{Gint}	T _j = 25 °C			0.00		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 125 °C		25		ns
t _r	I _C = 25 A	T _j = 125 °C		19		ns
E _{on}	V _{GE} = ±15 V	T _j = 125 °C		3.9		mJ
t _{d(off)}	R _{G on} = 16 Ω	T _j = 125 °C		184		ns
t _f	R _{G off} = 16 Ω	T _j = 125 °C		8		ns
E _{off}		T _j = 125 °C		1.6		mJ
R _{th(j-c)}	per IGBT				0.56	K/W



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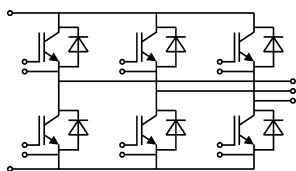
Features

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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 40 A	T _j = 25 °C		2.13	2.65	V
	V _{GE} = 0 V chipllevel	T _j = 125 °C		1.94	2.46	V
V _{F0}	chipllevel	T _j = 25 °C		1.1	1.45	V
		T _j = 125 °C		0.85	1.2	V
r _F	chipllevel	T _j = 25 °C		25.7	30.0	mΩ
		T _j = 125 °C		27.1	31.4	mΩ
I _{RRM}	I _F = 25 A	T _j = 125 °C		50		A
Q _{rr}	di/dt _{off} = 2500 A/μs	T _j = 125 °C		4		μC
E _{rr}	V _{GE} = ±15 V V _{CC} = 600 V	T _j = 125 °C		1.1		mJ
R _{th(j-c)}	per diode				1	K/W
Module						
L _{CE}					60	nH
R _{CC'+EE'}	terminal-chip	T _C = 25 °C				mΩ
		T _C = 125 °C				mΩ
R _{th(c-s)}	per module				0.05	K/W
M _s	to heat sink M6		4		5	Nm
M _t						Nm
						Nm
w					175	g



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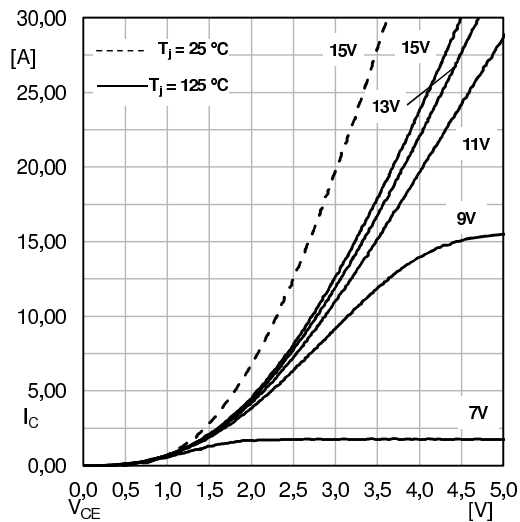


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + E_{E'}$

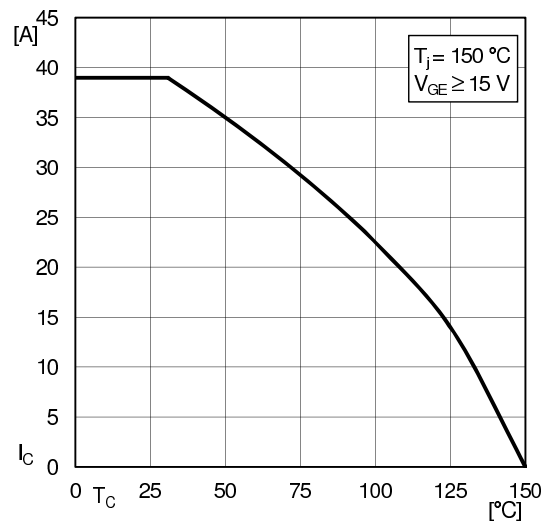


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

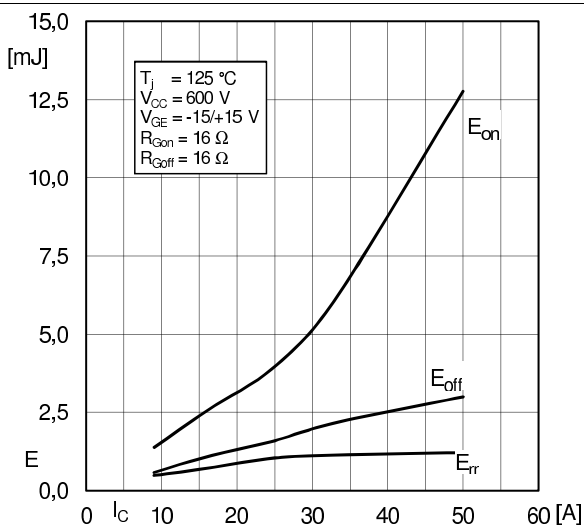


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

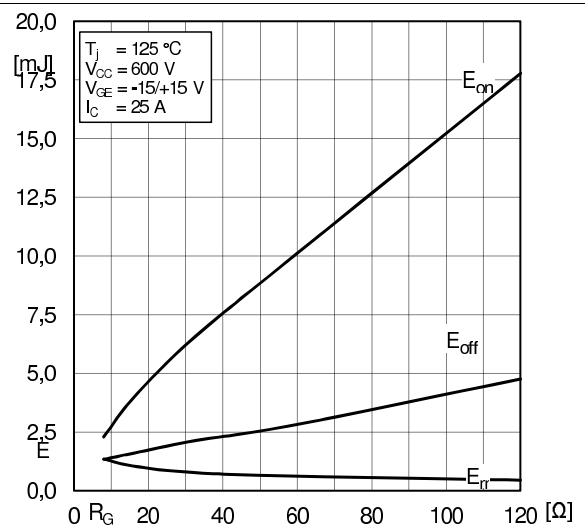


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

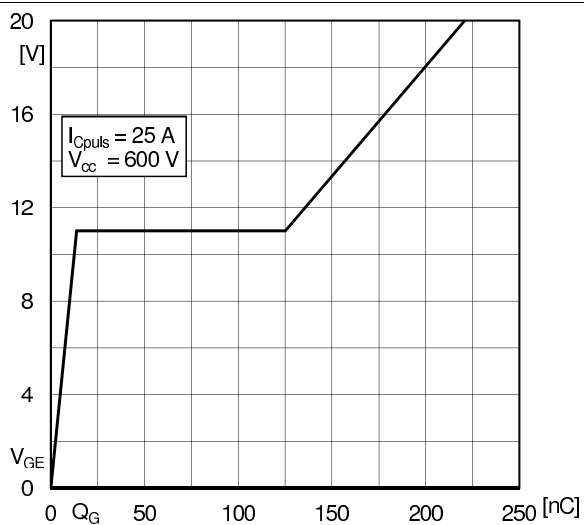


Fig. 6: Typ. gate charge characteristic

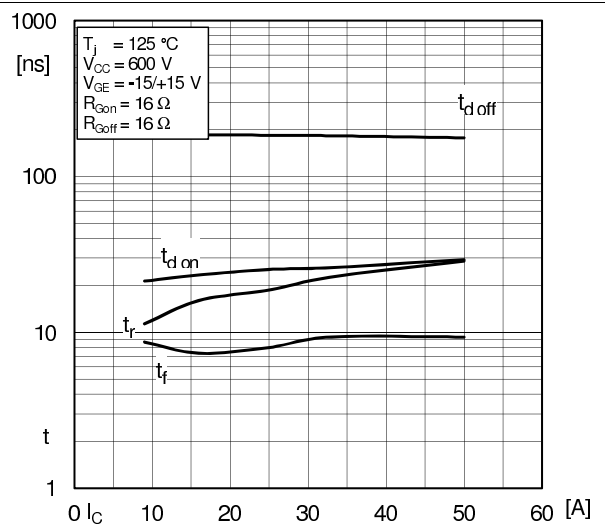


Fig. 7: Typ. switching times vs. I_C

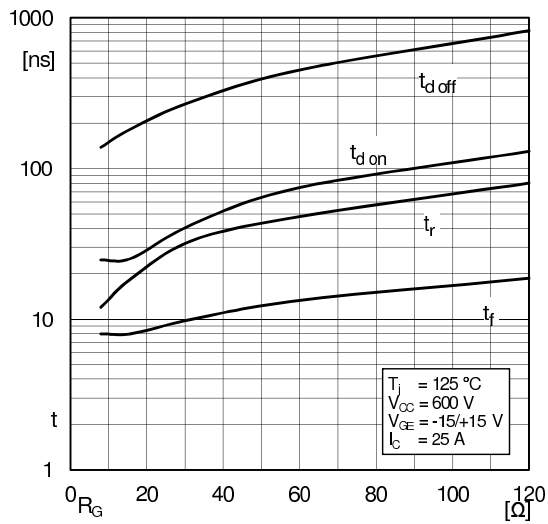


Fig. 8: Typ. switching times vs. gate resistor R_G

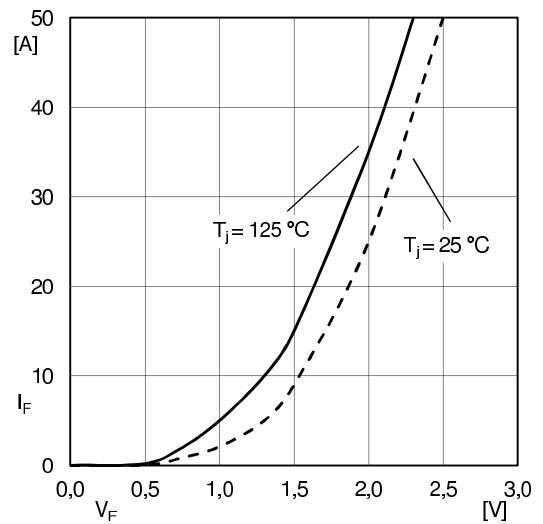
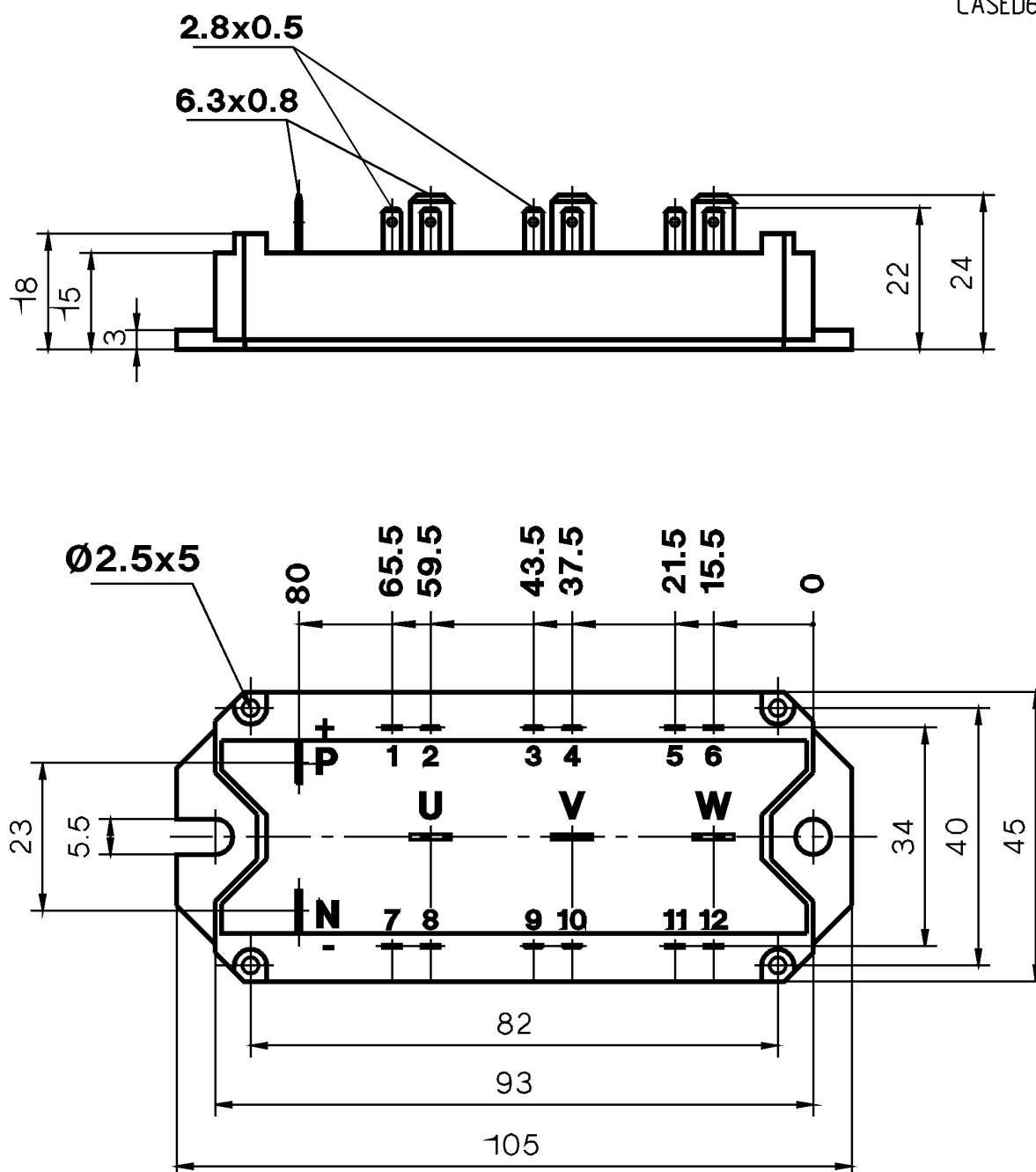
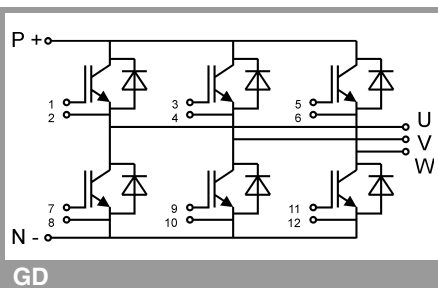


Fig. 10: Typ. CAL diode forward charact., incl. R_{CC'+EE'}



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.